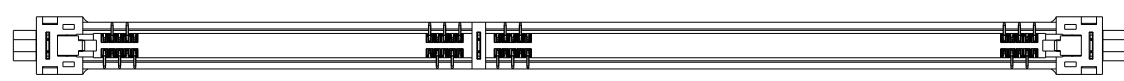
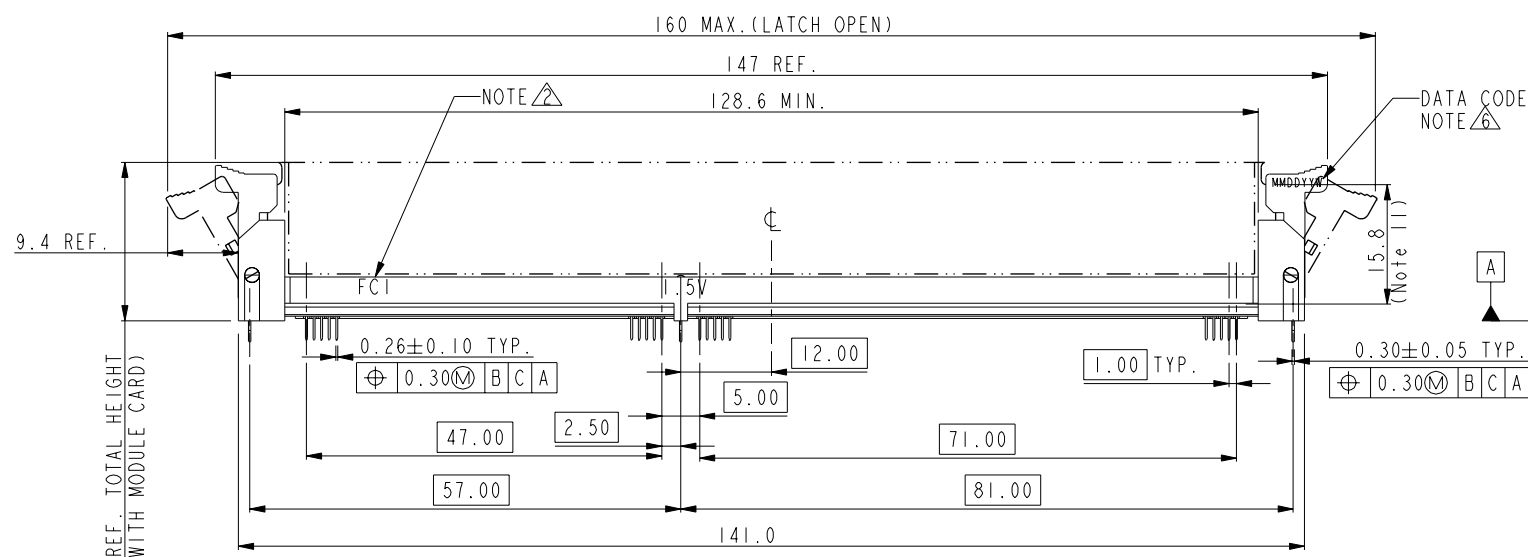
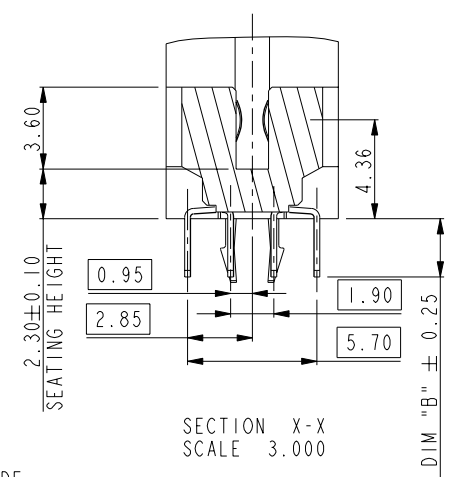
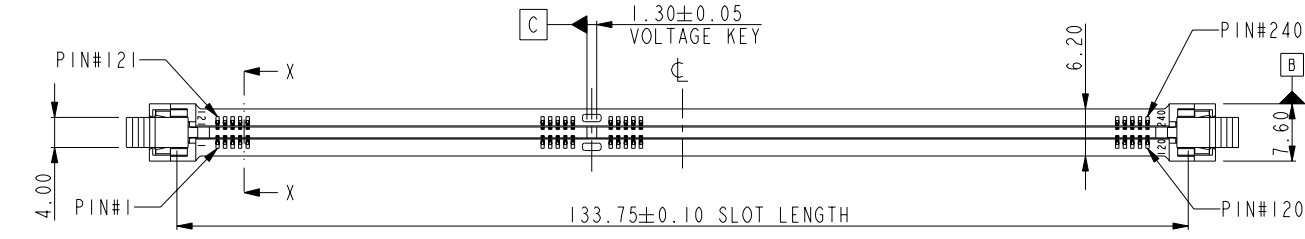




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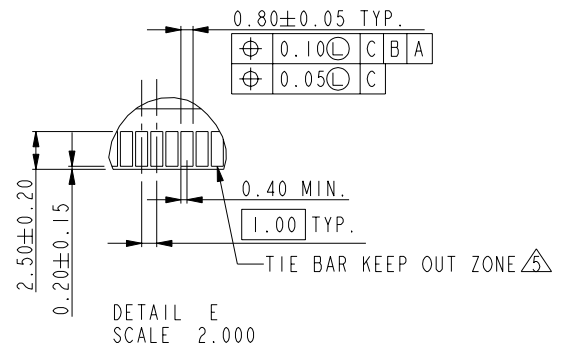
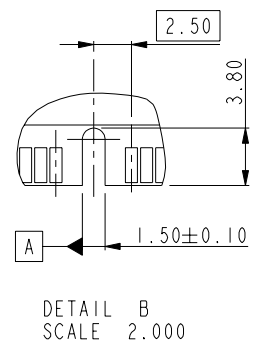
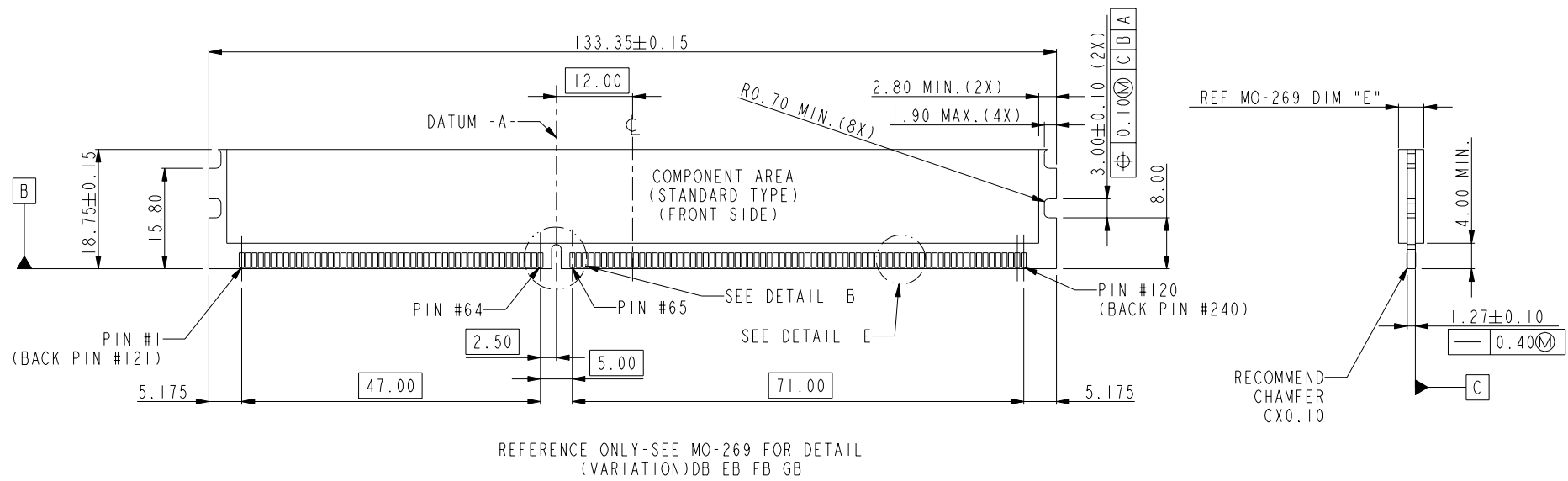
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A	DG08-0020	R C	01/14/2008
B	DG08-0064	R C	03/20/2008
C	DG08-0200	R C	07/31/2008
D	T09-1069	R C	05/13/2009
-	-	-	-
-	-	-	-
-	-	-	-

www.fciconnect.com		surface	<input checked="" type="checkbox"/>	tolerance std	projection	MM
		TOLERANCES UNLESS OTHERWISE SPECIFIED				
Dr	RICHARD CHIU	04/12/2007	ANGULAR	0.X	±0.38	size A4
Eng	RICHARD CHIU	04/12/2007	LINEAR	0.XX	±0.25	Scale 0.707
Chr	PAUL WANG	04/12/2007	0° ±5°	0.XXX	±0.13	ECN DG08-0233
Appr	JOSEPH HSIA	04/12/2007	Product family	-	Spec ref	*
		title	VERY LOW PROFILE (VLP) T.H		dwg no	10078239
		catalog no	-		CUSTOMER	Rev. D
				sheet 1 of 4		

REV F - 2006-04-17



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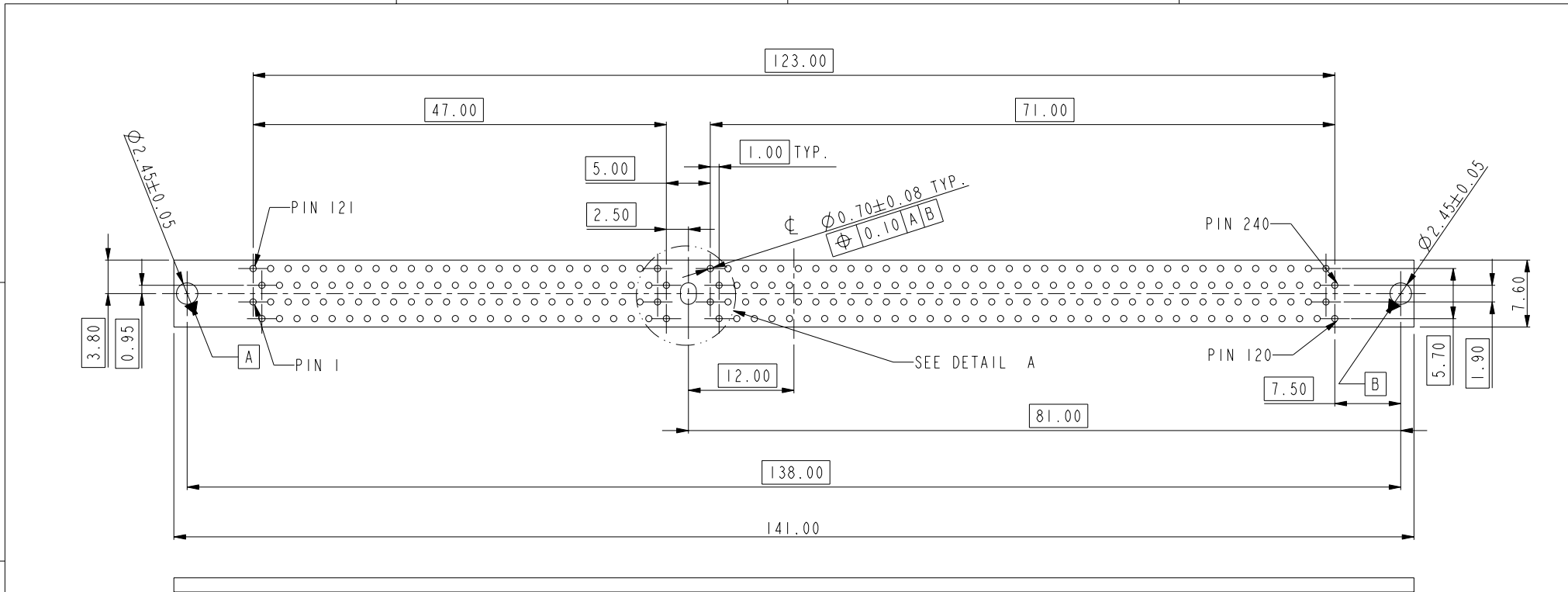


www.fciconnect.com		surface	-	tolerance std		projection	MM
		TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	RICHARD CHIU	04/12/2007	ANGULAR	0.X	±0.38	size	A4
Eng	RICHARD CHIU	04/12/2007	LINEAR	0.XX	±0.25	Scale	1.000
Chr	PAUL WANG	04/12/2007	0° ±5°	0.XXX	±0.13	ECN	DG08-0233
Appr	JOSEPH HSIA	04/12/2007	Product family			Spec ref	*
FCI		title	VERY LOW PROFILE (VLP) T.H		dwg no	10078239	
			DDR3, 240P MEMORY SOCKET (FOR UDIMM)			Rev.	D
		catalog no			CUSTOMER	sheet 2 of 4	

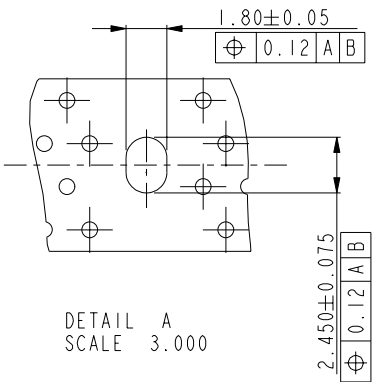
REV F - 2006-04-11



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RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



www.fciconnect.com			surface	<input checked="" type="checkbox"/>	tolerance std	projection	MM			
			TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	RICHARD CHIU	04/12/2007	ANGULAR	LINEAR	0.X	±0.38	size	A4	Scale	0.707
Eng	RICHARD CHIU	04/12/2007			0.XX	±0.25			ECN	DG08-0233
Chr	PAUL WANG	04/12/2007			0.XXX	±0.13			Spec ref	*
Appr	JOSEPH HSIA	04/12/2007	Product family							
		title	VERY LOW PROFILE (VLP) T.H				dwg no	10078239	Rev.	D
			DDR3, 240P MEMORY SOCKET (FOR UDIMM)							
		catalog no					CUSTOMER	sheet 3 of 4		

REV F - 2006-04-11

10078239 - □ □ □ □

STYLE : MECHANICAL KEYING
1 : 1.5 VOLT. W/ CENTER KEY

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
1LF	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
2LF	15u" (0.38um) MIN. GOLD		
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

CONTACT & FORKLICK LENGTH

CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 MM (0.063")
11	3.18 mm	4.00 mm	2.36 MM (0.093")

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 2 : BLACK HOUSING + BLACK EJECTOR
- 8 : IVORY HOUSING + IVORY EJECTOR
- 9 : IVORY HOUSING + BLACK EJECTOR



NOTES:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
TERMINAL: HIGH PERFORMANCE COPPER ALLOY
METAL CLIP: COPPER ALLOY.
2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-368.
4. PACKAGING SPECIFICATION: GS-14-899.
5. FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
6. THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE.
7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X.(SUSPENDED BY JEDEC)
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
10. THE HOUSING WILL WITH STAND EXPOSURE TO 260 ± 5°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
11. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.

www.fciconnect.com			surface <input checked="" type="checkbox"/>	tolerance std	projection	MM		
			TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	RICHARD CHIU	04/12/2007	ANGULAR	LINEAR	0.X	±0.38	size A4	Scale 1.000
Eng	RICHARD CHIU	04/12/2007			0.XX	±0.25	ECN	DG08-0233
Chr	PAUL WANG	04/12/2007	0°	±5°	0.XXX	±0.13		
Appr	JOSEPH HSIA	04/12/2007	Product family			Spec ref *		
			VERY LOW PROFILE (VLP) T.H			dwg no	10078239	Rev. D
			DDR3, 240P MEMORY SOCKET (FOR UDIMM)			CUSTOMER		sheet 4 of 4
			catalog no					